

MOS INTEGRATED CIRCUIT μ PD16772

480-OUTPUT TFT-LCD SOURCE DRIVER (COMPATIBLE WITH 64-GRAY SCALES)

DESCRIPTION

The μ PD16772 is a source driver for TFT-LCDs capable of dealing with displays with 64-gray scales. Data input is based on digital input configured as 6 bits by 6 dots (2 pixels), which can realize a full-color display of 260,000 colors by output of 64 values γ -corrected by an internal D/A converter and 5-by-2 external power modules. Because the output dynamic range is as large as Vss₂ + 0.1 V to Vdd - 0.1 V, level inversion operation of the LCD's common electrode is rendered unnecessary. Also, to be able to deal with dot-line inversion, n-line inversion and column line inversion when mounted on a single side, this source driver is equipped with a built-in 6-bit D/A converter circuit whose odd output pins and even output pins respectively output gray scale voltages of differing polarity. Assuring a clock frequency of 45 MHz when driving at 2.3 V, this driver is applicable to UXGA-standard TFT-LCD panels.

FEATURES

- CMOS level input (2.3 to 3.6 V)
- 480 outputs
- Input of 6 bits (gradation data) by 6 dots
- Capable of outputting 64 values by means of 5-by-2 external power modules (10 units) and a D/A converter (R-DAC)
- Output dynamic range: Vss2 + 0.1 V to Vdd2 0.1 V
- High-speed data transfer : fclk = 45 MHz (internal data transfer speed when operating at VDD1 = 2.3 V)
- Apply for dot-line inversion, n-line inversion and column line inversion
- Output voltage polarity inversion function (POL)
- Display data inversion function (POL21/22)
- Current consumption reduction function (LPC, Bcont)
- Logic power supply voltage (VDD1): 2.3 to 3.6 V
- Driver power supply voltage (V_{DD2}): 8.5 V \pm 0.5 V

ORDERING INFORMATION

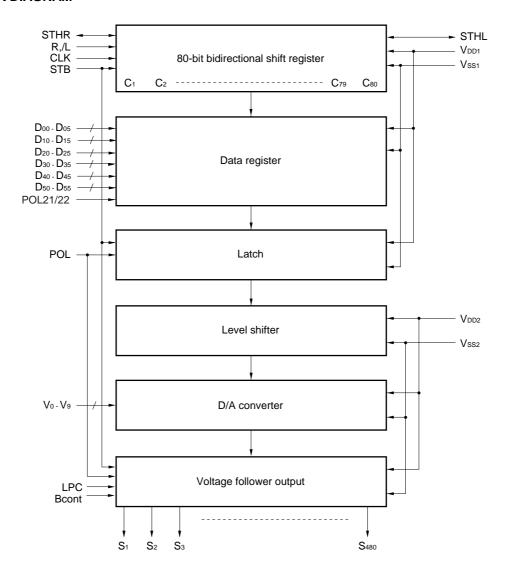
Part Number	Package
μ PD16772N-xxx	TCP (TAB package)

Remark The TCP's external shape is customized. To order the required shape, so please contact one of our sales representatives.

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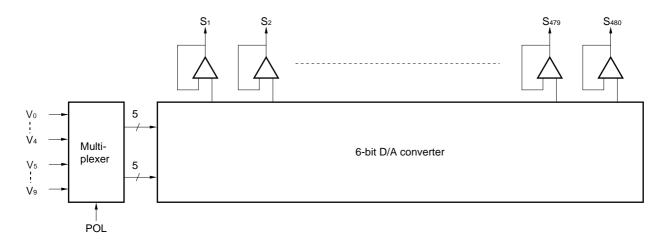
Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

1. BLOCK DIAGRAM



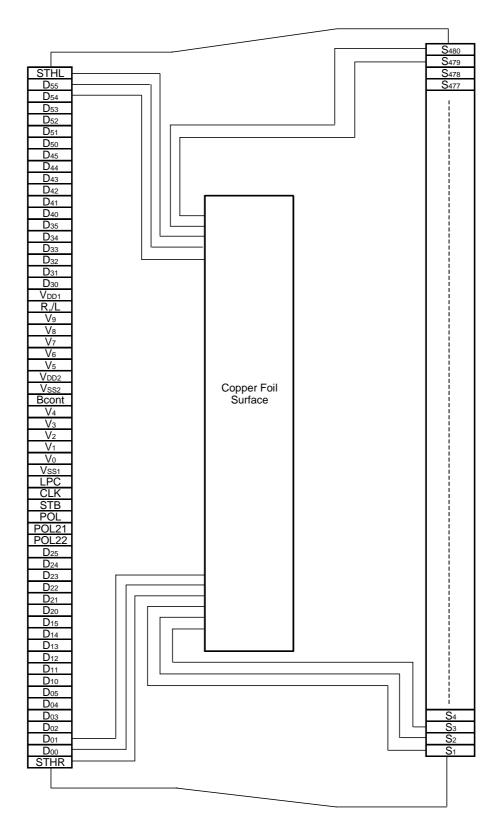
Remark /xxx indicates active low signal.

2. RELATIONSHIP BETWEEN OUTPUT CIRCUIT AND D/A CONVERTER





3. PIN CONFIGURATION (µPD16772N-xxx: TCP (TAB package))



Remark This figure does not specify the TCP package.



4. PIN FUNCTIONS

Pin Symbol	Pin Name	Description
S ₁ to S ₄₈₀	Driver output	The D/A converted 64-gray-scale analog voltage is output.
D ₀₀ to D ₀₅	Display data input	The display data is input with a width of 36 bits, viz., the gray scale data (6 bits) by 6 dots (2
D ₁₀ to D ₁₅		pixels).
D ₂₀ to D ₂₅		Dxo: LSB, Dxs: MSB
D ₃₀ to D ₃₅		
D ₄₀ to D ₄₅		
D50 to D55		
R,/L	Shift direction control input	These refer to the start pulse I/O pins when driver ICs are connected in cascade. The shift directions of the shift registers are as follows. R,/L = H: STHR input, $S_1 \rightarrow S_{480}$, STHL output R,/L = L: STHL input, $S_{480} \rightarrow S_1$, STHR output
STHR	Right shift start pulse	
	input/output	Fetching of display data starts when H is read at the rising edge of CLK.
STHL	Left shift start pulse	R,/L = H (right shift): STHR input, STHL output
	input/output	R,/L = L (left shift): STHL input, STHR output
OLIK	Ole Manual and a few months	The start pulse width (H level) for next-level drivers is 1CLK.
CLK	Shift clock input	Refers to the shift register's shift clock input. The display data is incorporated into the data register at the rising edge. At the rising edge of the 80th clock after the start pulse input, the start pulse output reaches the high level, thus becoming the start pulse of the next-level driver. If 82 clock pulses are input after input of the start pulse, input of display data is halted automatically. The contents of the shift register are cleared at the STB's rising edge.
STB	Latch input	The contents of the data register are transferred to the latch circuit at the rising edge. And,
		at the falling edge, the gray scale voltage is supplied to the driver. It is necessary to ensure
POL	Polarity input	input of one pulse per horizontal period. POL = L: The S_{2n-1} output uses V_0 to V_4 as the reference supply. The S_{2n} output uses V_5 to
. 02	l cianty input	V ₉ as the reference supply.
		POL = H: The S_{2n-1} output uses V_5 to V_9 as the reference supply. The S_{2n} output uses V_0 to
		V ₄ as the reference supply.
		S_{2n-1} indicates the odd output: and S_{2n} indicates the even output. Input of the POL signal is
		allowed the setup time(tpol-stb) with respect to STB's rising edge.
POL21,	Data inversion input	Data inversion can invert when display data is loaded.
POL22		POL21/22 = H : Data inversion loads display data after inverting it.
		POL21/22 = L : Data inversion does not invert input data.
		POL21: Doo to Do5, D10 to D15, D20 to D25
LPC	Low power central	POL22: D ₃₀ to D ₃₅ , D ₄₀ to D ₄₅ , D ₅₀ to D ₅₅ The current consumption of V _{DD2} is lowered by controlling the constant current source of the
LPC	Low power control input	output amplifier. This pin is pulled up to the V _{DD1} power supply inside the IC. For details,
	input	see 9. CURRENT CONSUMPTION REDUCTION FUNCTION.
Bcont	Bias control	This pin can be used to finely control the bias current inside the output amplifier.
		When this fine-control function is not required, leave this pin open. For details, see
		9. CURRENT CONSUMPTION REDUCTION FUNCTION.
Vo to V9	γ -corrected power	Input the γ -corrected power supplies from outside by using operational amplifier. Make sure
	supplies	to maintain the following relationships. During the gray scale voltage output, be sure to keep
		the gray scale level power supply at a constant level.
		$V_{DD2} - 0.1 \ V > V_0 > V_1 > V_2 > V_3 > V_4 > 0.5 \ V_{DD2} > V_5 > V_6 > V_7 > V_8 > V_9 > V_{SS2} + 0.1 \ V_{SS2} + 0.$
V _{DD1}	Logic power supply	2.3 to 3.6 V
V _{DD2}	Driver power supply	8.5 V ± 0.5 V
Vss ₁	Logic ground	Grounding
Vss2	Driver ground	Grounding



- Cautions 1. The power start sequence must be V_{DD1}, logic input, and V_{DD2} & V₀ to V₉ in that order.

 Reverse this sequence to shut down (Simultaneous power application to V_{DD2} and V₀ to V₉ is possible.).
 - 2. To stabilize the supply voltage, please be sure to insert a 0.1 μ F bypass capacitor between V_{DD1}-V_{SS1} and V_{DD2}-V_{SS2}. Furthermore, for increased precision of the D/A converter, insertion of a bypass capacitor of about 0.01 μ F is also advised between the γ -corrected power supply terminals (V₀, V₁, V₂,...., V₉) and V_{SS2}.

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5. RELATIONSHIP BETWEEN INPUT DATA AND OUTPUT VOLTAGE VALUE

The μ PD16772 incorporates a 6-bit D/A converter whose odd output pins and even output pins output respectively gray scale voltages of differing polarity with respect to the LCD's counter electrode (common electrode) voltage. The D/A converter consists of ladder resistors and switches.

The ladder resistors (r0 to r62) are designed so that the ratio of LCD panel γ -compensated voltages to Vo' to V63' and V6" to V63' is almost equivalent. For the 2 sets of five γ -compensated power supplies, V6 to V4 and V5 to V9, respectively, input gray scale voltages of the same polarity with respect to the common voltage. When fine gray scale voltage precision is not necessary, there is no need to connect a voltage follower circuit to the γ -compensated power supplies V1 to V3 and V6 to V8.

Figure 5–1 shows the relationship between the driving voltages such as liquid-crystal driving voltages VDD2 and VSS2, common electrode potential VCOM, and γ -corrected voltages V0 to V9 and the input data. Be sure to maintain the voltage relationships of VDD2 – 0.1 V > V0 > V1 > V2 > V3 > V4 > 0.5 VDD2 > V5 > V6 > V7 > V8 > V9 > VSS2 + 0.1 V

Figures 5–2 and 5–3 show the relationship between the input data and the output voltage and the resistance values of the resistor strings.

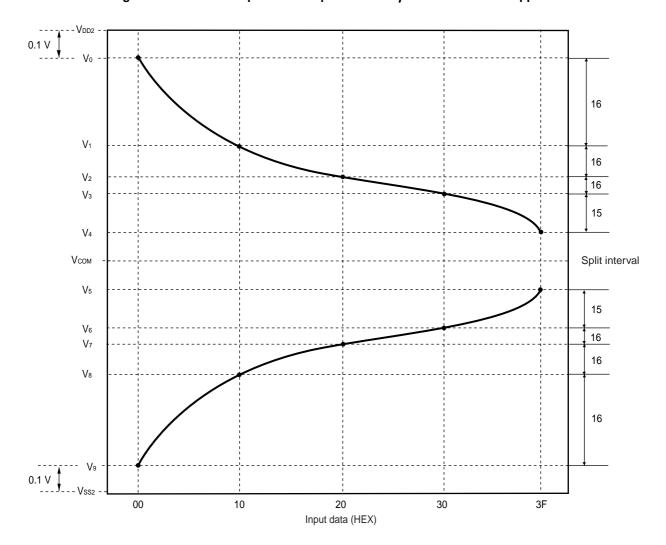


Figure 5–1. Relationship between Input Data and γcorrected Power Supplies



Figure 5–2. Relationship between Input Data and Output Voltage $V_{DD2} - 0.2 \ V > V_0 > V_1 > V_2 > V_3 > V_4 > 0.5 \ V_{DD2}, \ POL21/22 = L$

			Data	DX5	DX4	DX3	DX2	DX1	DX0		Output votage	rn	(Ω)
V ₀ —		V₀'	00H	0	0	0	0	0	0	V0'	V0	r0	800
r0	П		01H	0	0	0	0	0	1	V1'	V1+(V0-V1)× 7250 / 8050	r1	750
	I-	V₁'	02H	0	0	0	0	1	0	V2'	V1+(V0-V1)× 6500 / 8050	r2	700
r1			03H	0	0	0	0	1	1	V3'	V1+(V0-V1)× 5800 / 8050	r3	650
	I-	V₂'	04H	0	0	0	1	0	0	V4'	V1+(V0-V1)× 5150 / 8050	r4	600
r2			05H	0	0	0	1	0	1	V5'	V1+(V0-V1)× 4550 / 8050	r5	550
	I	→ V ₃ '	06H	0	0	0	1	1	0	V6' V7'	V1+(V0-V1)× 4000 / 8050	r6	550
r3	Ш		07H	0	0	0	0	0	0	V7'	V1+(V0-V1)× 3450 / 8050 V1+(V0-V1)× 2950 / 8050	r7 r8	500
	į		08H 09H	0	0	1	0	0	1	V9'	V1+(V0-V1)x 2950 / 8050	r9	500 400
	1		0AH	0	0	1	0	1	0	V10'	V1+(V0-V1)x 2450 / 8050	r10	400
	1		0BH	0	0	1	0	1	1	V11'	V1+(V0-V1)× 1650 / 8050	r11	350
			0CH	0	0	1	1	0	0	V12'	V1+(V0-V1)× 1300 / 8050	r12	350
	<u>i</u>		0DH	0	0	1	1	0	1	V13'	V1+(V0-V1)× 950 / 8050	r13	350
r14			0EH	0	0	1	1	1	0	V14'	V1+(V0-V1)× 600 / 8050	r14	300
		V ₁₅ ′	0FH	0	0	1	1	1	1	V15'	V1+(V0-V1)× 300 / 8050	r15	300
r15	Ш		10H	0	1	0	0	0	0	V16'	V1	r16	300
V1 —		→ V ₁₆ '	11H	0	1	0	0	0	1	V17	V2+(V1-V2)× 2450 / 2750	r17	250
r16	П		12H	0	1	0	0	1	0	V18'	V2+(V1-V2)× 2200 / 2750	r18	250
	I	→ V ₁₇ '	13H	0	1	0	0	1	1	V19'	V2+(V1-V2)× 1950 / 2750	r19	250
r17			14H 15H	0	1	0	1	0	0	V20' V21'	V2+(V1-V2)× 1700 / 2750 V2+(V1-V2)× 1500 / 2750	r20 r21	200
	T		16H	0	1	0	1	1	0	V21'	V2+(V1-V2)× 1500 / 2750 V2+(V1-V2)× 1300 / 2750	r22	200
			17H	0	1	0	1	1	1	V23'	V2+(V1-V2)× 1300 / 2750	r23	150
			18H	0	1	1	0	0	0	V24'	V2+(V1-V2)× 950 / 2750	r24	150
	- 1		19H	0	1	1	0	0	1	V25'	V2+(V1-V2)× 800 / 2750	r25	150
	i		1AH	0	1	1	0	1	0	V26'	V2+(V1-V2)× 650 / 2750	r26	150
	- 1		1BH	0	1	1	0	1	1	V27'	V2+(V1-V2)× 500 / 2750	r27	100
	1		1CH	0	1	1	1	0	0	V28'	V2+(V1-V2)× 400 / 2750	r28	100
			1DH	0	1	1	1	0	1	V29'	V2+(V1-V2)× 300 / 2750	r29	100
	- 1		1EH	0	1	1	1	1	0	V30'	V2+(V1-V2)× 200 / 2750	r30	100
	į		1FH	0	1	1	1	1	1	V31'	V2+(V1-V2)× 100 / 2750	r31	100
			20H	1	0	0	0	0	0	V32'	V2	r32	100
	1		21H 22H	1	0	0	0	0	0	V33' V34'	V3+(V2-V3)× 1500 / 1600 V3+(V2-V3)× 1400 / 1600	r33 r34	100 100
			23H	1	0	0	0	1	1	V35'	V3+(V2-V3)× 1400 / 1600	r35	100
	- 1		24H	1	0	0	1	0	0	V36'	V3+(V2-V3)× 1200 / 1600	r36	100
	i		25H	1	0	0	1	0	1	V37'	V3+(V2-V3)× 1100 / 1600	r37	100
			26H	1	0	0	1	1	0	V38'	V3+(V2-V3)× 1000 / 1600	r38	100
			27H	1	0	0	1	1	1	V39'	V3+(V2-V3)× 900 / 1600	r39	100
	i		28H	1	0	1	0	0	0	V40'	V3+(V2-V3)× 800 / 1600	r40	100
	- 1		29H	1	0	1	0	0	1	V41'	V3+(V2-V3)× 700 / 1600	r41	100
	i		2AH	1	0	1	0	1	0	V42'	V3+(V2-V3)× 600 / 1600	r42	100
	- 1		2BH	1	0	1	0	1	1	V43'	V3+(V2-V3)× 500 / 1600	r43	100
r46	\Box		2CH 2DH	1	0	1	1	0	1	V44' V45'	V3+(V2-V3)× 400 / 1600 V3+(V2-V3)× 300 / 1600	r44 r45	100 100
	7_	→ V ₄₇ '	2EH	1	0	1	1	1	0	V45 V46'	V3+(V2-V3)× 300 / 1600 V3+(V2-V3)× 200 / 1600	r46	100
r47			2FH	1	0	1	1	1	1	V47'	V3+(V2-V3)× 100 / 1600	r47	100
V3 —	Τ_	→ V ₄₈ '	30H	1	1	0	0	0	0	V48'	V3	r48	100
r48	\Box		31H	1	1	0	0	0	1	V49'	V4+(V3-V4)× 3350 / 3450	r49	100
	Τ-	→ V ₄₉ '	32H	1	1	0	0	1	0	V50'	V4+(V3-V4)× 3250 / 3450	r50	100
r49	П		33H	1	1	0	0	1	1	V51'	V4+(V3-V4)× 3150 / 3450	r51	100
	Ţ		34H	1	1	0	1	0	0	V52'	V4+(V3-V4)× 3050 / 3450	r52	100
	į		35H	1	1	0	1	0	1	V53'	V4+(V3-V4)× 2950 / 3450	r53	150
			36H	1	1	0	1	1	0	V54'	V4+(V3-V4)× 2800 / 3450	r54	150
	1		37H	1	1	0	1	1	1	V55'	V4+(V3-V4)× 2650 / 3450	r55	150
	- 1		38H	1	1	1	0	0	0	V56'	V4+(V3-V4)× 2500 / 3450	r56	200
r60	$\dot{\Box}$		39H 3AH	1	1	1	0	0 1	0	V57' V58'	V4+(V3-V4)× 2300 / 3450 V4+(V3-V4)× 2100 / 3450	r57 r58	200 250
100	닏	→ V ₆₁ '	3AH 3BH	1	1	1	0	1	1	V58 V59'	V4+(V3-V4)× 2100 / 3450 V4+(V3-V4)× 1850 / 3450	r59	250
r61	Щ	·· V 61	3CH	1	1	1	1	0	0	V60'	V4+(V3-V4)× 1600 / 3450	r60	300
	ᆛ	→ V ₆₂ '	3DH	1	1	1	1	0	1	V61'	V4+(V3-V4)× 1300 / 3450	r61	500
r62	亡	V 62	3EH	1	1	1	1	1	0	V62'	V4+(V3-V4)× 800 / 3450	r62	800
	Y		3FH	1	1	1	1	1	1	V63'	V4	r total	15850
V4 -		→ V ₆₃ '	·				-						

Caution There is no connection between V_4 and V_5 terminal in the chip.

Figure 5–3. Relationship between Input Data and Output Voltage $0.5 \text{ V}_{DD2} > \text{V}_5 > \text{V}_6 > \text{V}_7 > \text{V}_8 > \text{V}_9 > \text{V}_{SS2} + 0.1 \text{ V}, POL21/22 = L$

			Data	DX5	DX4	DX3	DX2	DX1	DX0		Output voltage	rn	(Ω)
V ₅	$\overline{}$	V ₆₃ "	00H	0	0	0	0	0	0	V0"	V9	r0	800
r62	· ·		01H	0	0	0	0	0	1	V1"	V9+(V8-V9)× 800 / 8050	r1	750
		V ₆₂ "	02H	0	0	0	0	1	0	V2"	V9+(V8-V9)× 1550 / 8050	r2	700
r61	Ш		03H	0	0	0	0	1	1	V3"	V9+(V8-V9)× 2250 / 8050	r3	650
	Τ	→ V ₆₁ "	04H	0	0	0	1	0	0	V4"	V9+(V8-V9)× 2900 / 8050	r4	600
r60	\Box		05H	0	0	0	1	0	1	V5"	V9+(V8-V9)× 3500 / 8050	r5	550
	ᅮ_	→ V ₆₀ ''	06H	0	0	0	1	1	0	V6"	V9+(V8-V9)× 4050 / 8050	r6	550
r59	\Box		07H	0	0	0	1	1	1	V7"	V9+(V8-V9)× 4600 / 8050	r7	500
	7		H80	0	0	1	0	0	0	V8" V9"	V9+(V8-V9)× 5100 / 8050	r8 r9	500
			09H	0	0	1	0	1	0	V9 V10"	V9+(V8-V9)× 5600 / 8050 V9+(V8-V9)× 6000 / 8050	r10	400 400
	1		0AH 0BH	0	0	1	0	1	1	V10"	V9+(V8-V9)× 6000 / 8050 V9+(V8-V9)× 6400 / 8050	r11	350
			0CH	0	0	1	1	0	0	V11"	V9+(V8-V9)× 6750 / 8050	r12	350
	1		0DH	0	0	1	1	0	1	V12"	V9+(V8-V9)× 7100 / 8050	r13	350
r49	\Box		0EH	0	0	1	1	1	0	V14"	V9+(V8-V9)× 7450 / 8050	r14	300
	Ŧ	→ V ₄₉ "	0FH	0	0	1	1	1	1	V15"	V9+(V8-V9)× 7750 8050	r15	300
r48	\Box		10H	0	1	0	0	0	0	V16"	V8	r16	300
V ₆ —	ㅜ_	V ₄₈ "	11H	0	1	0	0	0	1	V17"	V8+(V7-V8)× 300 / 2750	r17	250
r47	П		12H	0	1	0	0	1	0	V18"	V8+(V7-V8)× 550 / 2750	r18	250
	\top	V47"	13H	0	1	0	0	1	1	V19"	V8+(V7-V8)× 800 / 2750	r19	250
r46			14H	0	1	0	1	0	0	V20"	V8+(V7-V8)× 1050 / 2750	r20	200
	T		15H	0	1	0	1	0	1	V21"	V8+(V7-V8)× 1250 / 2750	r21	200
	- 1		16H	0	1	0	1	1	0	V22"	V8+(V7-V8)× 1450 / 2750	r22	200
	i		17H	0	1	0	1	1	1	V23"	V8+(V7-V8)× 1650 / 2750	r23	150
			18H	0	1	1	0	0	0	V24"	V8+(V7-V8)× 1800 / 2750	r24	150
	1		19H	0	1	1	0	0	1	V25"	V8+(V7-V8)× 1950 / 2750	r25	150
			1AH	0	1	1	0	1	0	V26"	V8+(V7-V8)× 2100 / 2750	r26	150
	- 1		1BH	0	1	1	0	1	1	V27"	V8+(V7-V8)× 2250 / 2750	r27	100
	1		1CH	0	1	1	1	0	0	V28"	V8+(V7-V8)× 2350 / 2750	r28	100
			1DH	0	1	1	1	0	1	V29"	V8+(V7-V8)× 2450 / 2750	r29	100
	1		1EH	0	1	1	1	1	0	V30"	V8+(V7-V8)× 2550 / 2750	r30	100
			1FH	0	1	1	1	1	1	V31"	V8+(V7-V8)× 2650 2750	r31	100
			20H	1	0	0	0	0	0	V32"	V7	r32	100
	i		21H 22H	1	0	0	0	1	0	V33" V34"	V7+(V6-V7)× 100 / 1600 V7+(V6-V7)× 200 / 1600	r33 r34	100 100
			23H	1	0	0	0	1	1	V34"	V7+(V6-V7)× 200 / 1600 V7+(V6-V7)× 300 / 1600	r35	100
	1		24H	1	0	0	1	0	0	V36"	V7+(V6-V7)× 300 / 1600	r36	100
			25H	1	0	0	1	0	1	V37"	V7+(V6-V7)× 500 / 1600	r37	100
			26H	1	0	0	1	1	0	V38"	V7+(V6-V7)× 600 / 1600	r38	100
r17	П		27H	1	0	0	1	1	1	V39"	V7+(V6-V7)× 700 / 1600	r39	100
	\perp	V ₁₇ "	28H	1	0	1	0	0	0	V40"	V7+(V6-V7)× 800 / 1600	r40	100
r16			29H	1	0	1	0	0	1	V41"	V7+(V6-V7)× 900 / 1600	r41	100
V ₈ —	-I-	V16"	2AH	1	0	1	0	1	0	V42"	V7+(V6-V7)× 1000 / 1600	r42	100
r15			2BH	1	0	1	0	1	1	V43"	V7+(V6-V7)× 1100 / 1600	r43	100
	\perp	—► V15"	2CH	1	0	1	1	0	0	V44"	V7+(V6-V7)× 1200 / 1600	r44	100
r14	Ш		2DH	1	0	1	1	0	1	V45"	V7+(V6-V7)× 1300 / 1600	r45	100
			2EH	1	0	1	1	1	0	V46"	V7+(V6-V7)× 1400 / 1600	r46	100
	1		2FH	1	0	1	1	1	1	V47"	V7+(V6-V7)× 1500 / 1600	r47	100
			30H	1	1	0	0	0	0	V48"	V6	r48	100
			31H	1	1	0	0	0	1	V49"	V6+(V5-V6)× 100 / 3450	r49	100
	i		32H	1	1	0	0	1	0	V50"	V6+(V5-V6)× 200 / 3450	r50	100
			33H	1	1	0	0	1	1	V51"	V6+(V5-V6)× 300 / 3450	r51	100
	÷		34H	1	1	0	1	0	0	V52"	V6+(V5-V6)× 400 / 3450	r52	100
r2	Ļ		35H	1	1	0	1	0	1	V53"	V6+(V5-V6)× 500 / 3450	r53	150
		 V₂"	36H	1	1	0	1	1	0	V54"	V6+(V5-V6)× 650 / 3450	r54	150
r1	Ļ		37H	1	1	0	1	1	1	V55"	V6+(V5-V6)x 800 / 3450	r55	150
	上	─ V₁"	38H 39H	1	1	1	0	0	1	V56" V57"	V6+(V5-V6)× 950 / 3450 V6+(V5-V6)× 1150 / 3450	r56 r57	200
r0	Ц		39H 3AH	1	1	1	0	1	0	V57 V58"	V6+(V5-V6)× 1150 / 3450 V6+(V5-V6)× 1350 / 3450	r58	250
V ₉ —		 V₀''	3BH	1	1	1	0	1	1	V50"	V6+(V5-V6)× 1330 / 3450 V6+(V5-V6)× 1600 / 3450	r59	250
			3CH	1	1	1	1	0	0	V60"	V6+(V5-V6)× 1850 / 3450	r60	300
			3DH	1	1	1	1	0	1	V61"	V6+(V5-V6)× 2150 / 3450	r61	500
			3EH	1	1	1	1	1	0	V62"	V6+(V5-V6)× 2650 / 3450	r62	800
			3FH	1	1	1	1	1	1	V63"	V5	rtotal	15850
									<u> </u>				

Caution There is no connection between V4 and V5 terminal in the chip.



6. RELATIONSHIP BETWEEN INPUT DATA AND OUTPUT PIN

Data format : 6 bits x 2 RGBs (6 dots) Input width : 36 bits (2-pixel data)

(1) $R_{,}/L = H$ (Right shift)

Output	S ₁	S ₂	S ₃	S ₄	 S ₄₇₉	S ₄₈₀
Data	D ₀₀ to D ₀₅	D ₁₀ to D ₁₅	D ₂₀ to D ₂₅	D ₃₀ to D ₃₅	 D40 to D45	D50 to D55

(2) R,/L = L (Left shift)

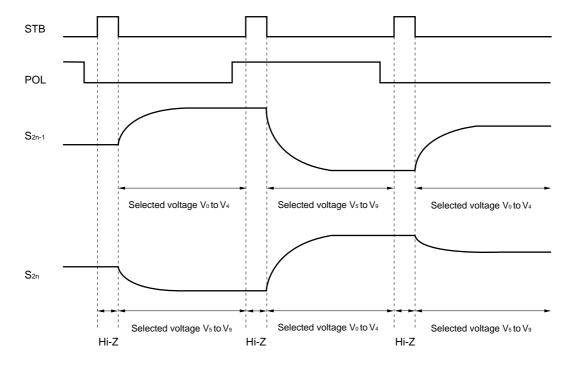
Output	S ₁	S ₂	S3	S4	 S479	S ₄₈₀
Data	Doo to Dos	D ₁₀ to D ₁₅	D ₂₀ to D ₂₅	D ₃₀ to D ₃₅	 D ₄₀ to D ₄₅	D50 to D55

POL	S _{2n-1} Note	S _{2n} Note
L	Vo to V4	V ₅ to V ₉
Н	V ₅ to V ₉	V ₀ to V ₄

Note S_{2n-1} (Odd output), S_{2n} (Even output)

7. RELATIONSHIP BETWEEN STB, POL AND OUTPUT WAVEFORM

The output voltage is written to the LCD panel synchronized with the STB falling edge.



8. RELATIONSHIP BETWEEN STB, CLK AND OUTPUT WAVEFORM

The output voltage is written to the LCD panel synchronized with the STB falling edge.

Figure 8-1. Output Circuit Block Diagram

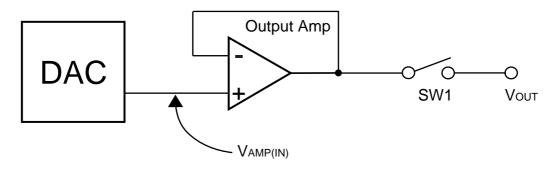
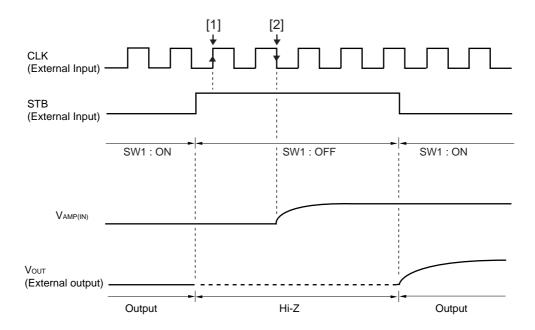


Figure 8–2. Output Circuit Timing Waveform



Remarks 1. STB = L : SW1 = ONSTB = H : SW1 = OFF

- 2. STB = "H" is acknowledged at timing [1].
- **3.** The display data latch is compensated at timing [2] and the input voltage (VAMP(IN): gray-scale level voltage) of the output amplifier changes.



9. CURRENT CONSUMPTION REDUCTION FUNCTION

The μ PD16772 has a low power control function (LPC) which can switch the bias current of the output amplifier between two levels and a bias control function (Bcont) which can be used to finely control the bias current.

• Low Power Control Function (LPC)

The bias current of the output amplifier can be switched between two levels using this pin (Bcont: Open).

LPC = H or Open: Low power mode

LPC = L: Normal power mode

The VDD2 of static current consumption can be reduced to two thirds of that in normal mode. Input a stable DC current (VDD1/VSS1) to this pin.

• Bias Current Control Function (Bcont)

 $20 \text{ k}\Omega$

0Ω

It is possible to fine-control the current consumption by using the bias current control function (Bcont pin). When using this function, connect this pin to the stabilized ground potential (Vss2) via an external resistor (Rext). When not using this function, leave this pin open.

μPD16772

Bcont LPC

REXT

Figure 9-1. Bias Current Control Function (Bcont)

Refer to the table below for the percentage of current regulation when using the bias current control function.

140%

240%

Table 9-1. Current Consumption Regulation Percentage Compared to Normal Mode

Remark The above current consumption regulation percentages are not product-characteristic guaranteed as they are based on the results of simulation.

100%

210%

Caution Because the low-power and bias-current control functions control the bias current in the output amplifier and regulate the over-all current consumption of the driver IC, when this occurs, the characteristics of the output amplifier will simultaneously change. Therefore, when using these functions, be sure to sufficiently evaluate the picture quality.

10. ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings (T_A = 25°C, V_{SS1} = V_{SS2} = 0 V)

Parameter	Symbol	Rating	Unit
Logic Part Supply Voltage	V _{DD1}	-0.5 to +4.0	V
Driver Part Supply Voltage	V _{DD2}	-0.5 to +10.0	V
Logic Part Input Voltage	V _{I1}	-0.5 to V _{DD1} + 0.5	V
Driver Part Input Voltage	V _{I2}	-0.5 to V _{DD2} + 0.5	V
Logic Part Output Voltage	Vo ₁	-0.5 to V _{DD1} + 0.5	V
Driver Part Output Voltage	V _{O2}	-0.5 to V _{DD2} + 0.5	V
Operating Ambient Temperature	TA	–10 to +75	°C
Storage Temperature	Tstg	-55 to +125	°C

★ Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Recommended Operating Range (T_A = -10 to +75°C, Vss₁ = Vss₂ = 0 V)

посетинением орогиину по	1	1	- '			
Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Logic Part Supply Voltage	V _{DD1}		2.3		3.6	V
Driver Part Supply Voltage	V _{DD2}		8.0	8.5	9.0	V
High-Level Input Voltage	Vін		0.7 V _{DD1}		V _{DD1}	V
Low-Level Input Voltage	VIL		0		0.3 V _{DD1}	V
γ -Corrected Voltage	V ₀ to V ₉		Vss2 + 0.1		V _{DD2} – 0.1	V
Driver Part Output Voltage	Vo		Vss2 + 0.1		V _{DD2} – 0.1	V
Clock Frequency	fclk	VDD2 = 2.3 V			45	MHz



Electrical Characteristics (TA = -10 to +75°C, VDD1 = 2.3 to 3.6 V, VDD2 = 8.5 V \pm 0.5 V, Vss1 = Vss2 = 0 V, unless otherwise specified, the input level is defined to be LPC = L, Bcont = Open)

Parameter	Symbol	Condition	on	MIN.	TYP.	MAX.	Unit
Input Leak Current	lıL					±1.0	μΑ
High-Level Output Voltage	Vон	STHR (STHL), Ion = 0	mA	V _{DD1} – 0.1			V
Low-Level Output Voltage	Vol	STHR (STHL), lot = 0 i	mA			0.1	V
γ -Corrected Supply Current	lγ	V _{DD2} = 8.5 V	V ₀ pin, V ₅ pin	126	252	504	μΑ
		V ₀ to V ₄ = V ₅ to V ₉ =	V4 pin, V9 pin	-504	-252	-126	μΑ
		4.0 V					
Driver Output Current	Іvон	Vx = 7.0 V, Vout = 6.5	V Note			-30	μΑ
	Ivol	VX = 1.0 V, Vout = 1.5	V Note	30			μΑ
Output Voltage Deviation	ΔVο	T _A = 25°C			±7	±20	mV
Output Swing Difference	ΔV _{P-P}	V _{DD1} = 3.3 V, V _{DD2} = 8.5	5 V		±2	±15	mV
Deviation		Vout = 2.0 V, 4.25 V, 6	.5 V				
Logic Part Dynamic Current	I _{DD1}	V _{DD1}			1.0	7.5	mA
Consumption							
Driver Part Dynamic Current	I _{DD2}	V _{DD2} , with no load		3.5	7.5	mA	
Consumption							

Note Vx refers to the output voltage of analog output pins S_1 to S_{480} .

Vout refers to the voltage applied to analog output pins S1 to S480.

- ★ Cautions 1. fstb = 50 kHz, fclk = 40 MHz
 - 2. The TYP. values refer to an all black or all white input pattern. The MAX. value refers to the measured values in the dot checkerboard input pattern.
 - 3. Refers to the current consumption per driver when cascades are connected under the assumption of UXGA single-sided mounting (10 units).

Switching Characteristics (TA = -10 to +75°C, VDD1 = 2.3 to 3.6 V, VDD2 = 8.5 V \pm 0.5 V, Vss1 = Vss2 = 0 V, unless otherwise specified, the input level is defined to be LPC = L, Bcont = Open)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Start Pulse Delay Time	t _{PLH1}	C _L = 10 pF		10	20	ns
	tPHL1			10	20	ns
Driver Output Delay Time	t PLH2	$C_L = 75 \text{ pF}, R_L = 5k\Omega$		2.5	5	μS
	t PLH3			5	8	μs
	t PHL2			2.5	5	μs
	tPHL3			5	8	μs
Input Capacitance	Cıı	STHR (STHL) excluded, T _A = 25°C		5	10	pF
	Cı2	STHR (STHL),TA = 25°C		8	10	pF

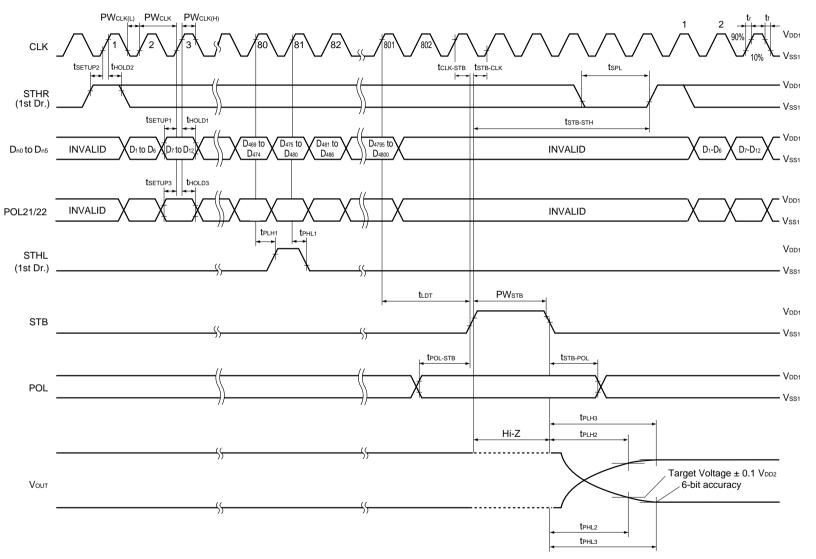
\star Timing Requirements (TA = -10 to +75°C, VDD1 = 2.3 to 3.6 V, Vss1 = 0 V, tr = tf = 5.0 ns)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Clock Pulse Width	PWclk	V _{DD1} = 2.3 to 3.6 V	22			ns
Clock Pulse High Period	PW _{CLK(H)}		4			ns
Clock Pulse Low Period	PW _{CLK(L)}	V _{DD1} = 2.3 to 3.0 V	7			ns
		V _{DD1} = 3.0 to 3.6 V	4			ns
Data Setup Time	tsetup1		3			ns
Data Hold Time	tHOLD1		0			ns
Start Pulse Setup Time	tsetup2		3			ns
Start Pulse Hold Time	tHOLD2		0			ns
POL21/22 Setup Time	tsetup3		3			ns
POL21/22 Hold Time	thold3	V _{DD1} = 2.3 to 3.0 V	1			ns
		V _{DD1} = 3.0 to 3.6 V	0			ns
Start Pulse Low Period	tspl		1			CLK
STB Pulse Width	PWstB		2			CLK
Last Data Timing	t ldt		2			CLK
CLK-STB Time	tclк-sтв	$CLK \uparrow \rightarrow STB \uparrow$	6			ns
STB-CLK Time	tsтв-сцк	$STB \uparrow \rightarrow CLK \uparrow$	14			ns
		V _{DD1} = 2.3 to 3.0 V				
		STB $\uparrow \rightarrow$ CLK \uparrow	6			ns
		V _{DD1} = 3.0 to 3.6 V				
Time Between STB and Start Pulse	tsтв-sтн	$STB \uparrow \rightarrow STHR(STHL) \uparrow$	2			CLK
POL-STB Time	tpol-stb	POL \uparrow or $\downarrow \rightarrow$ STB \uparrow	-5			ns
STB-POL Time	tstb-pol	$STB \downarrow \rightarrow POL \downarrow or \uparrow$	6			ns

Remark Unless otherwise specified, the input level is defined to be VIH = 0.7 VDD1, VIL = 0.3 VDD1.

SWITCHING CHARACTERISTIC WAVEFORM(R,/L= H)

Unless otherwise specified, the input level is defined to be $V_{IH} = 0.7 \text{ V}_{DD1}$, $V_{IL} = 0.3 \text{ V}_{DD1}$.



12. RECOMMENDED MOUNTING CONDITIONS

The following conditions must be met for mounting conditions of the $\mu PD16772$.

For more details, refer to the Semiconductor Device Mounting Technology Manual (C10535E).

Please consult with our sales offices in case other mounting process is used, or in case the mounting is done under different conditions.

μPD16772N-xxx : TCP (TAB Package)

Mounting Condition	Mounting Method	Condition
Thermocompression	Soldering	Heating tool 300 to 350°C, heating for 2 to 3 seconds : pressure 100g
		(per solder)
	ACF	Temporary bonding 70 to 100°C: pressure 3 to 8 kg/cm ² : time 3 to 5
	(Adhesive	sec. Real bonding 165 to 180°C: pressure 25 to 45 kg/cm ² : time 30 to
	Conductive Film)	40 sec. (When using the anisotropy conductive film SUMIZAC1003 of
		Sumitomo Bakelite,Ltd).

Caution To find out the detailed conditions for mounting the ACF part, please contact the ACF manufacturing company. Be sure to avoid using two or more mounting methods at a time.

[MEMO]

[MEMO]



NOTES FOR CMOS DEVICES

1 PRECAUTION AGAINST ESD FOR SEMICONDUCTORS

Note:

Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

2 HANDLING OF UNUSED INPUT PINS FOR CMOS

Note:

No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to VDD or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

3) STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note:

Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

Reference Documents

NEC Semiconductor Device Reliability/Quality Control System (C10983E)
Quality Grades to NEC's Semiconductor Devices (C11531E)

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 - "Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)
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